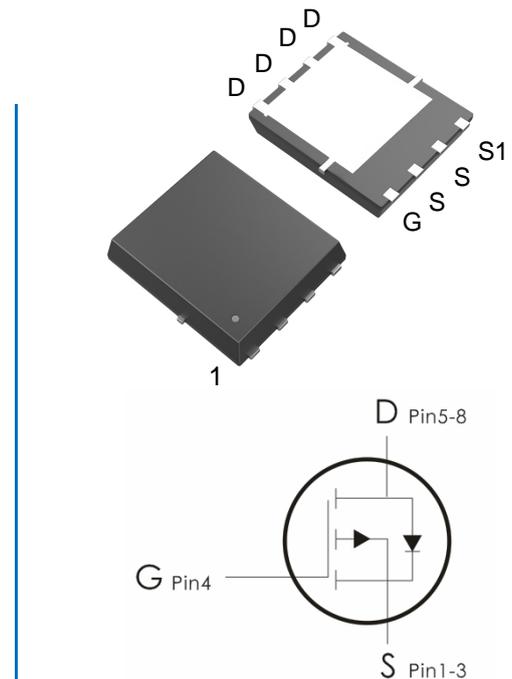


Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=-60V, I_D=-30A, R_{DS(ON)}<35m\Omega @V_{GS}=-10V$ (Typ: $28m\Omega$)
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.
- 6) MSL3



Package Marking and Ordering Information:

Part NO.	Marking	Package	Packing
NE035PG	E035P	DFN5*6-8	5000 pcs/Reel

Absolute Maximum Ratings: ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	-30	A
	Continuous Drain Current- $T_c=100^\circ\text{C}$	-19	
I_{DM}	Pulsed Drain Current ¹	-120	
P_D	Power Dissipation	45	W
E_{AS}	Single pulse avalanche energy ²	225	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55-+175	$^\circ\text{C}$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.8	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	42	$^\circ\text{C}/\text{W}$

Electrical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	-60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=-60V$	---	---	-1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	-1	-1.69	-2.5	V
$R_{DS(ON)}$	Drain-Source On Resistance ³	$V_{GS}=-10V, I_D=-15A$	---	28	35	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-30V, V_{GS}=0V, f=1\text{MHz}$	---	2535	---	pF
C_{oss}	Output Capacitance		---	130	--	
C_{rss}	Reverse Transfer Capacitance		---	75	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=-30V, I_D=-10A,$ $R_{ENG}=6.8\ \Omega, V_{GS}=-10V$	---	14	---	ns
t_r	Rise Time		---	18	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	42	---	ns
t_f	Fall Time		---	15	---	ns
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-30V,$ $I_D=-10A$	---	46	---	nC
Q_{gs}	Gate-Source Charge		---	11	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	10	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=-15A$	---	-0.88	-1.2	V
I_S	Continuous Drain Current	$V_D=V_G=0V$	---	---	-30	A
I_{SM}	Pulsed Drain Current		---	---	-120	A
T_{rr}	Reverse Recovery Time	$I_F=20A, T_J=25^\circ\text{C}$	---	28	---	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu\text{s}$	---	165	---	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition : $T_J=25^{\circ}\text{C}$, $V_{DD}=-30\text{V}$, $V_G=10\text{V}$, $L=0.5\text{mH}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Characteristics: ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

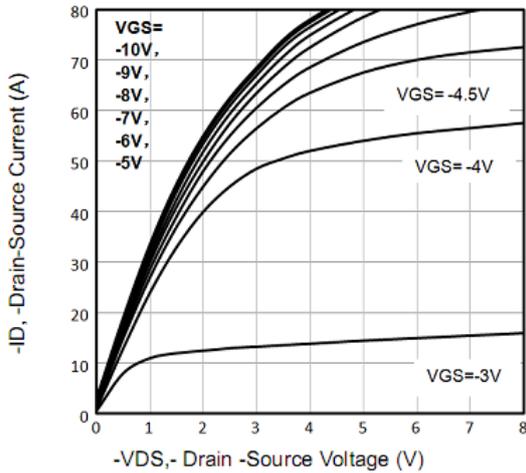


Fig1. Typical Output Characteristics

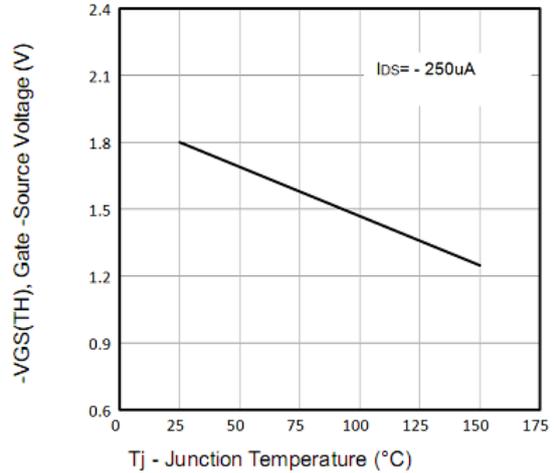


Fig2. $-V_{GS(TH)}$ Gate -Source Voltage Vs. T_J

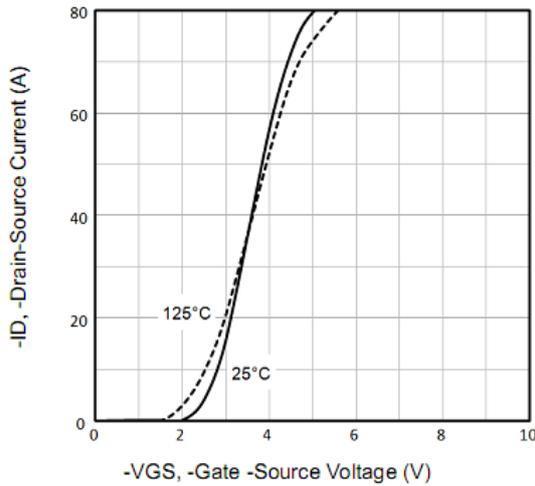


Fig3. Typical Transfer Characteristics

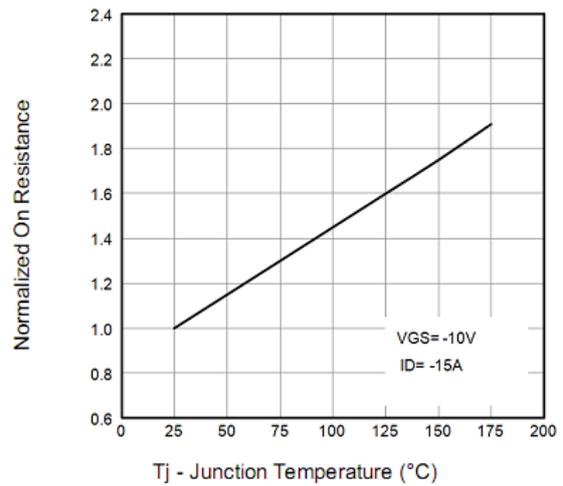


Fig4. Normalized On-Resistance Vs. T_J

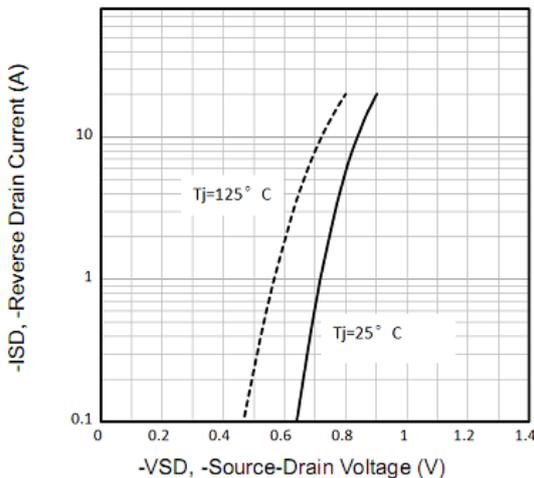


Fig5. Typical Source-Drain Diode Forward Voltage

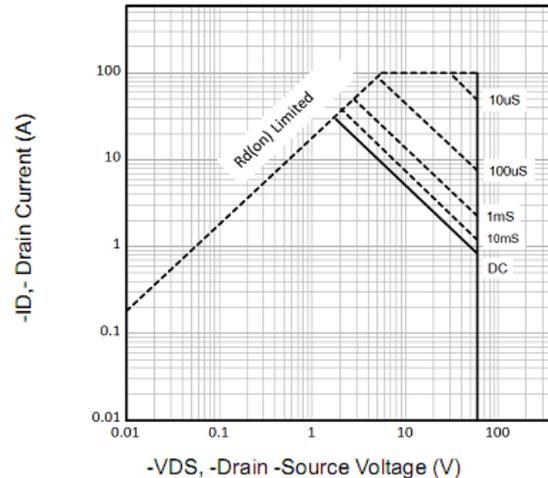


Fig6. Maximum Safe Operating Area

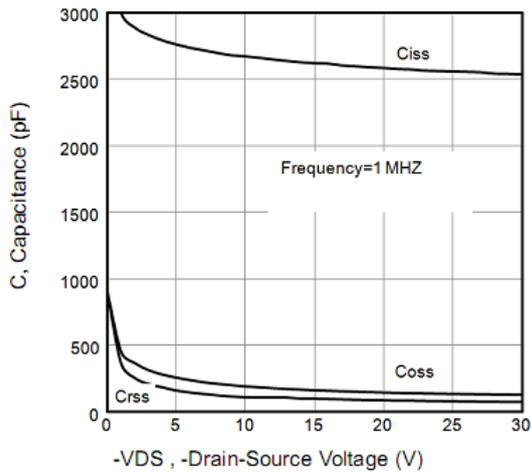


Fig7. Typical Capacitance Vs. Drain-Source Voltage

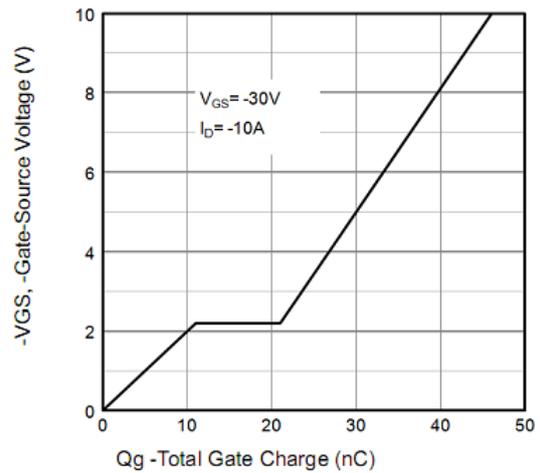


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

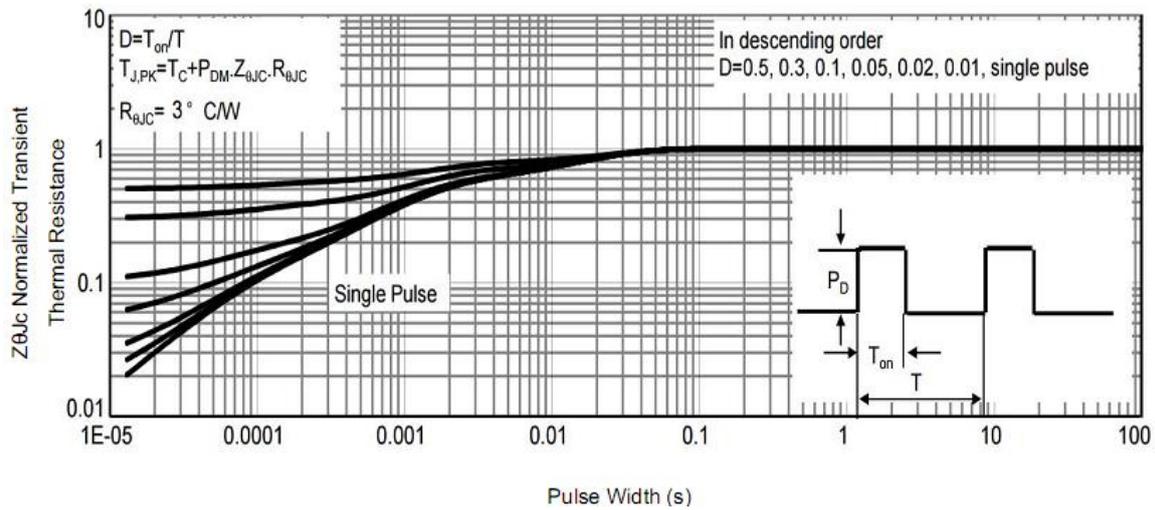


Fig9. Normalized Maximum Transient Thermal Impedance

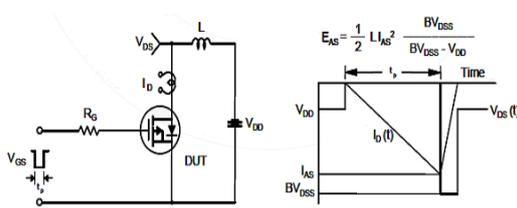


Fig10. Unclamped Inductive Test Circuit and Waveforms

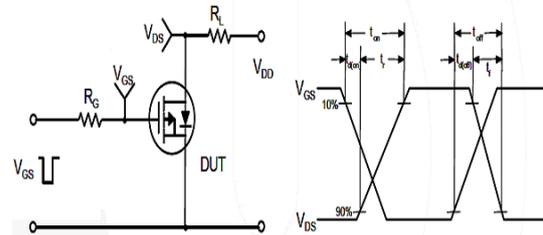
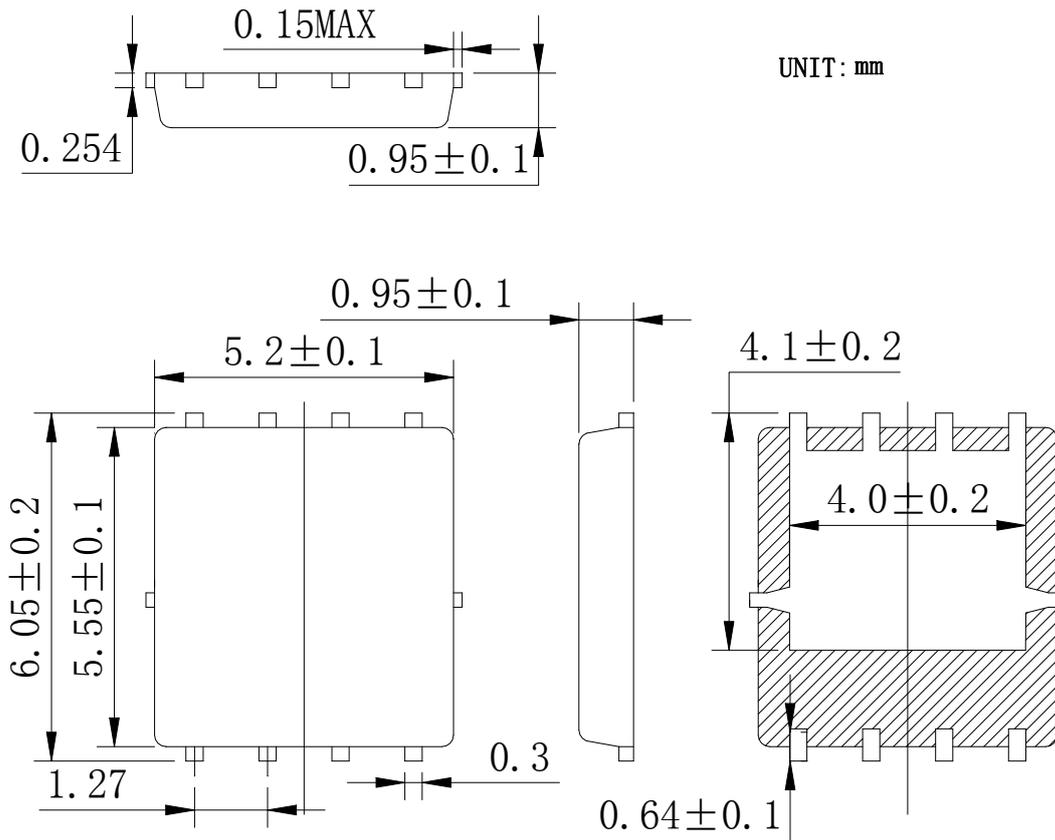


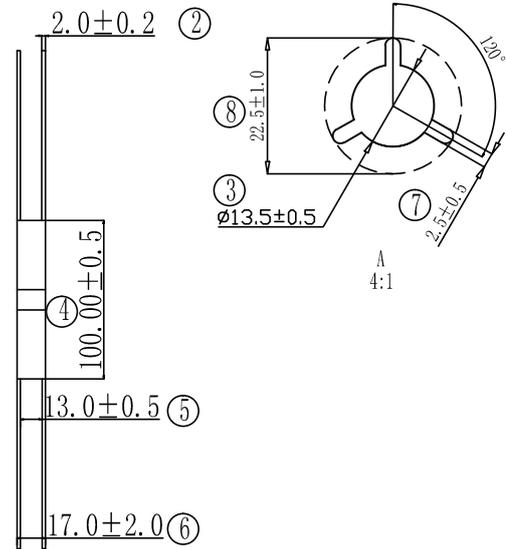
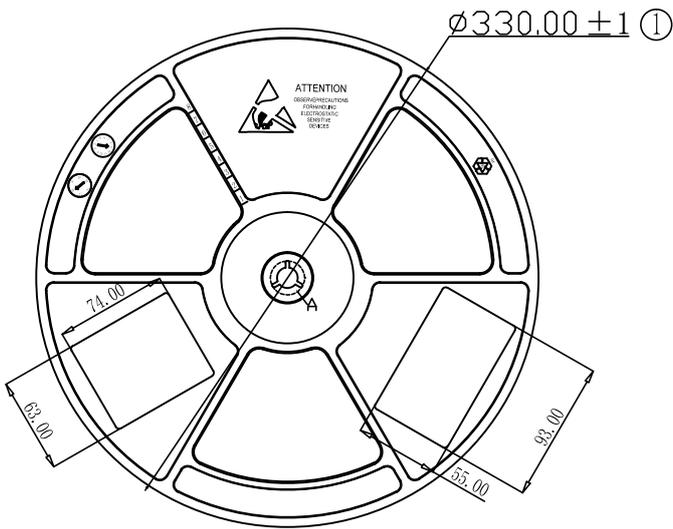
Fig11. Switching Time Test Circuit and waveforms

DFN5x6-8 Package Information:

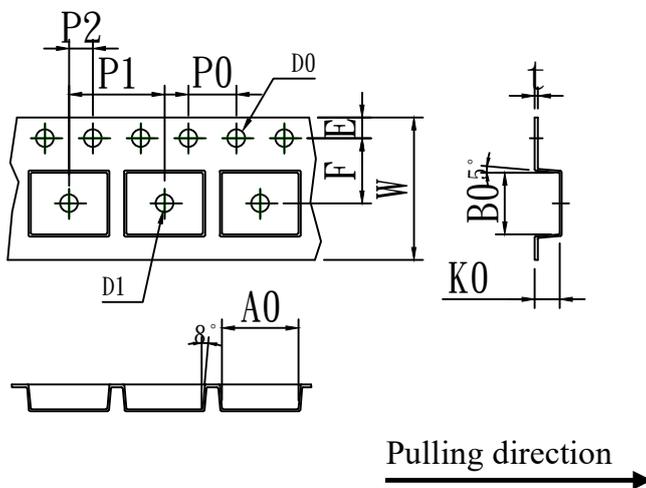


Tape & Reel Information

Dimensions in mm



Symbol	A0	B0	K0	D0	D1	P0	P1	10*P0
Spec	6.15 ± 0.10	5.40 ± 0.10	1.30 ± 0.10	1.55 ± 0.10	1.55 ± 0.10	4.00 ± 0.10	8.00 ± 0.10	40.00 ± 0.10
Symbol	W	E	F	P2	t			
Spec	12.00 ± 0.10	1.75 ± 0.10	5.50 ± 0.10	2.00 ± 0.10	0.20 ± 0.05			



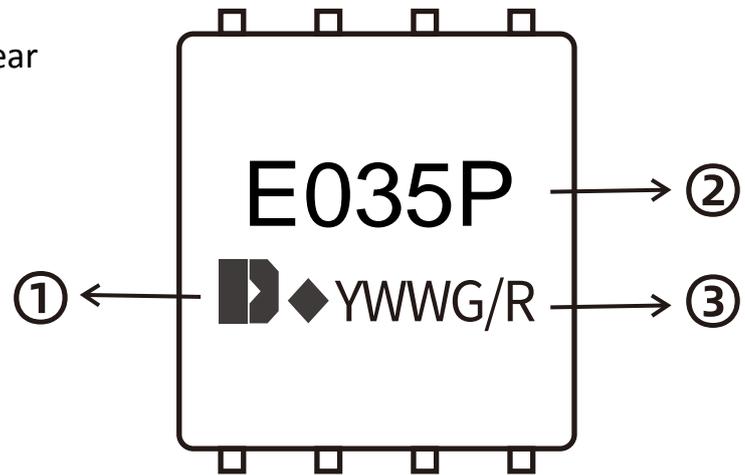
Marking Information:

- ①. Doingter LOGO
- ②. Part NO.
- ③. Date Code(YWWG / R)

Y : Year Code , last digit of the year

WW : Week Code(01-53)

G/R : G(Green) /R(Lead Free)



Previous Version

Version	Date	Subjects (major changes since last revision)
1.0	2024-12-12	Release of final version

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